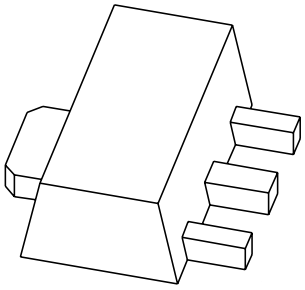
DATA SHEET



BCV29; BCV49
NPN Darlington transistors

Product data sheet
Supersedes data of 1999 Apr 08

2004 Dec 06

NPN Darlington transistors BCV29; BCV49

FEATURES

- High current (max. 500 mA)
- Low voltage (max. 60 V)
- High DC current gain (min. 20000).

APPLICATIONS

- Preamplifier input applications.

DESCRIPTION

NPN small-signal Darlington transistor in a surface mount SOT89 plastic package. PNP complements: BCV28 and BCV48.

MARKING

TYPE NUMBER	MARKING CODE
BCV29	EF
BCV49	EG

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

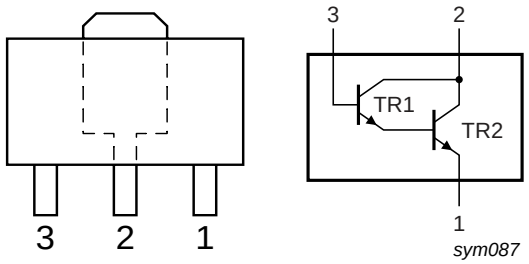


Fig.1 Simplified outline (SOT89) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCV29	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89
BCV49			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BCV29		−	40	V
	BCV49		−	80	V
V_{CES}	collector-emitter voltage	V_{BE} = 0 V			
	BCV29		−	30	V
	BCV49		−	60	V
V_{EBO}	emitter-base voltage	open collector	−	10	V
I_C	collector current (DC)		−	500	mA
I_{CM}	peak collector current		−	1	A
I_{BM}	peak base current		−	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	−	1.3	W
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		−	150	°C
T_{amb}	ambient temperature		−65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.
   For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook".*

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	96	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point		16	K/W

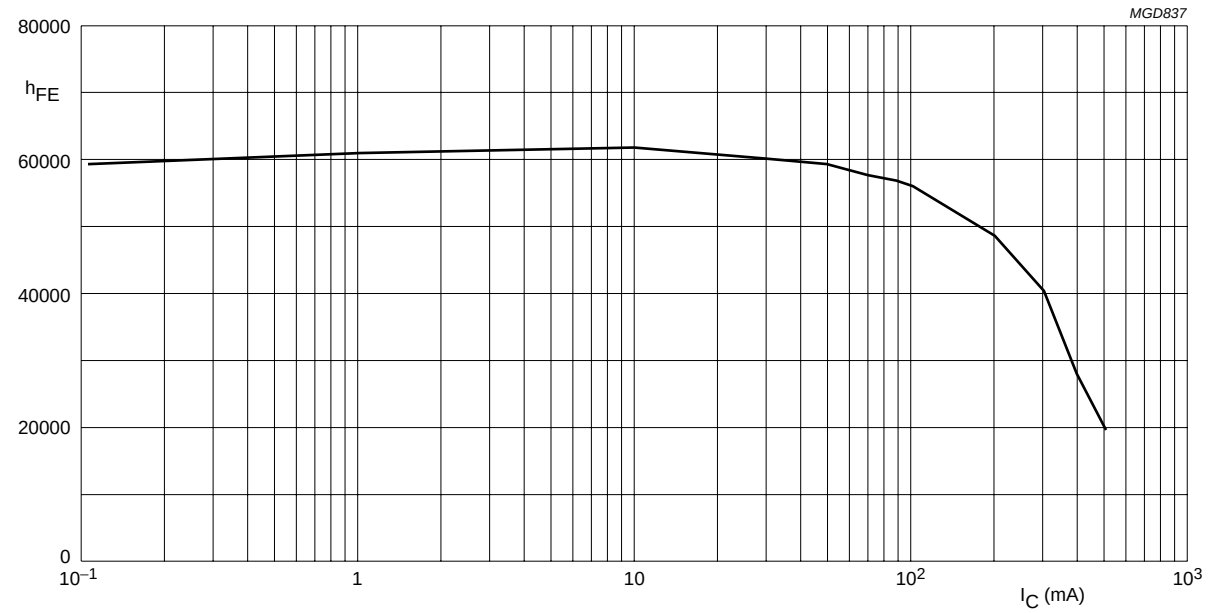
Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.
   For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook".*

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current					
	BCV29	I_E = 0 A; V_{CB} = 30 V	–	–	100	nA
	BCV49	I_E = 0 A; V_{CB} = 60 V	–	–	100	nA
I_{EBO}	emitter-base cut-off current	I_C = 0 A; V_{EB} = 10 V	–	–	100	nA
h_{FE}	DC current gain	V_{CE} = 5 V; see Fig.2				
	BCV29	I_C = 1 mA	4000	–	–	
		I_C = 10 mA	10000	–	–	
		I_C = 100 mA	20000	–	–	
		I_C = 500 mA	4000	–	–	
	DC current gain	V_{CE} = 5 V; see Fig.2				
	BCV49	I_C = 1 mA	2000	–	–	
		I_C = 10 mA	4000	–	–	
		I_C = 100 mA	10000	–	–	
		I_C = 500 mA	2000	–	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = 100 mA; I_B = 0.1 mA	–	–	1	V
V_{BEsat}	base-emitter saturation voltage	I_C = 100 mA; I_B = 0.1 mA	–	–	1.5	V
V_{BEon}	base-emitter on-state voltage	I_C = 10 mA; V_{CE} = 5 V	–	–	1.4	V
f_T	transition frequency	I_C = 30 mA; V_{CE} = 5 V; f = 100 MHz	–	220	–	MHz

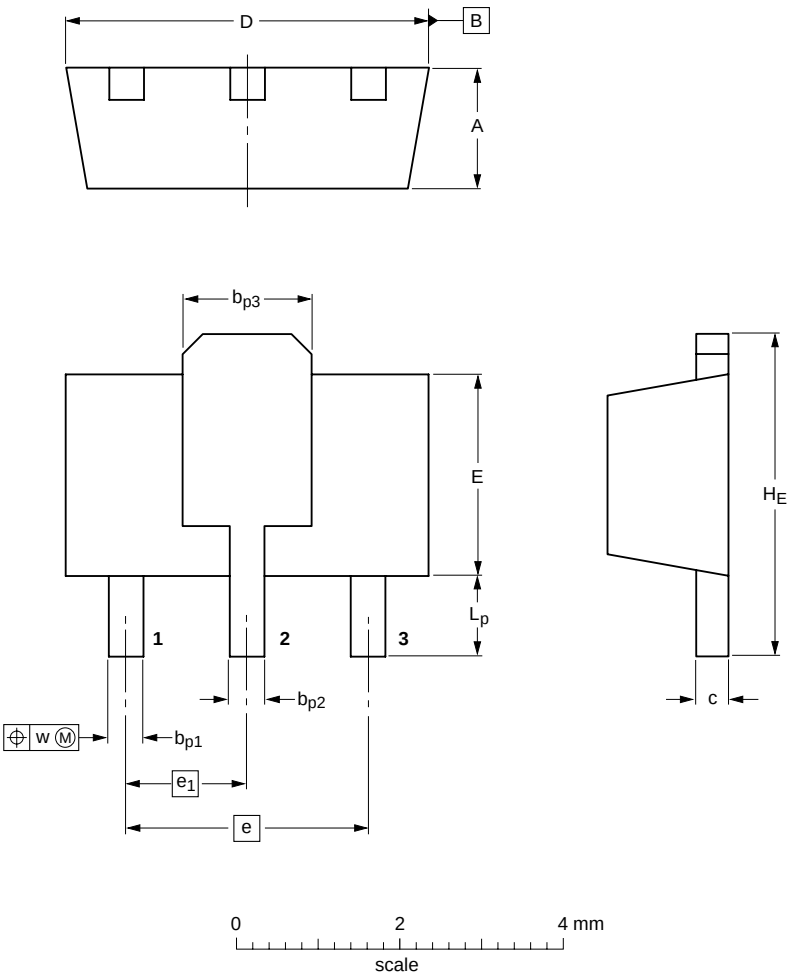


V_{CE} = 2 V.

Fig.2 DC current gain; typical values.

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads **SOT89**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_{p1}	b_{p2}	b_{p3}	c	D	E	e	e_1	H_E	L_p	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT89		TO-243	SC-62			~~04-08-03~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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